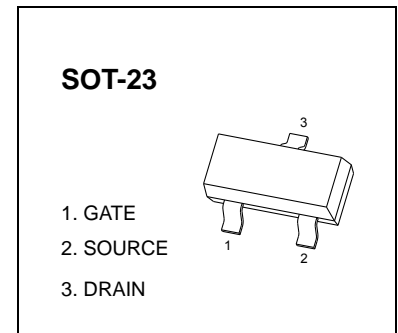


N-Channel Enhancement Mode Power MOSFET

$V_{(BR)DSS}$	$R_{DS(on)MAX}$	I_D
60V	3Ω@10V	300mA
	4 Ω@4.5V	



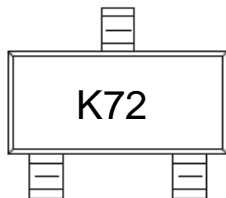
FEATURE

- High density cell design for Low $R_{DS(on)}$
- Voltage controlled small signal switch
- Rugged and reliable
- High saturation current capability
- ESD protected

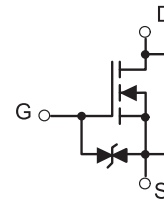
APPLICATION

- Load Switch for Portable Devices
- DC/DC Converter

“M5 F ?-B;



Equivalent circuit



MOSFET MAXIMUM RATINGS ($T_a = 25^\circ\text{C}$ unless otherwise noted)

Symbol	Parameter	Value	Unit
V_{DS}	Drain-Source voltage	60	V
V_{GS}	Gate-Source voltage	±20	V
I_D	Drain Current	300	mA
P_D	Power Dissipation	0.35	W
T_J	Junction Temperature	150	°C
T_{stg}	Storage Temperature	-55~+150	°C
$R_{\theta JA}$	Thermal Resistance from Junction to Ambient	357	°C /W

MOSFET ELECTRICAL CHARACTERISTICS
T_a = 25 °C unless otherwise specified

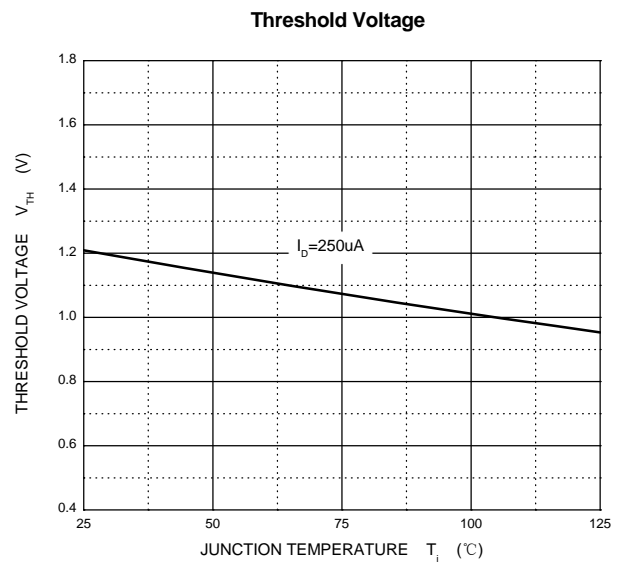
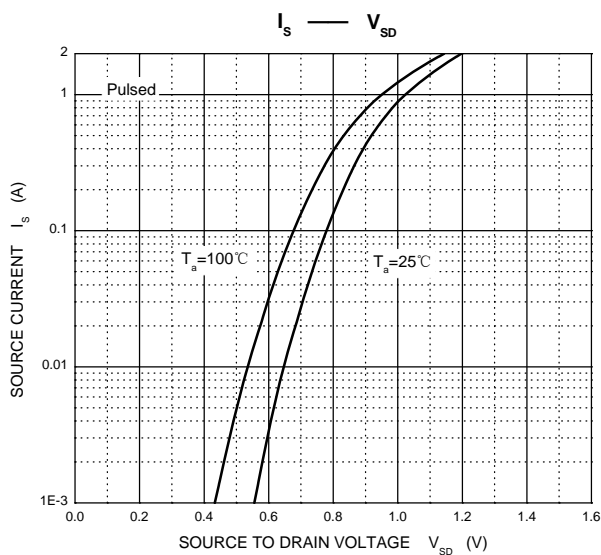
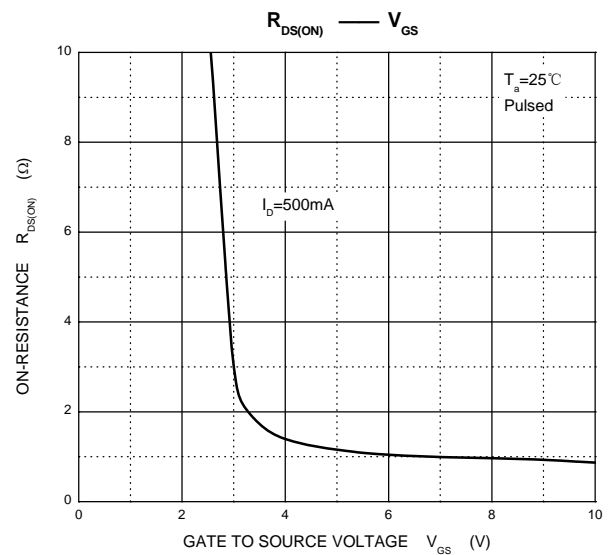
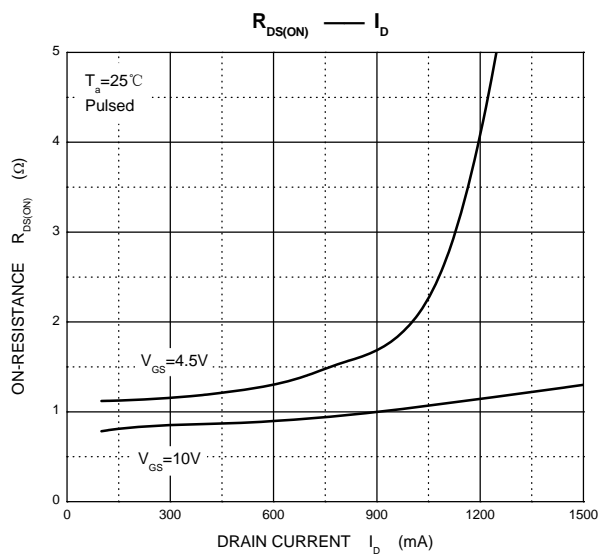
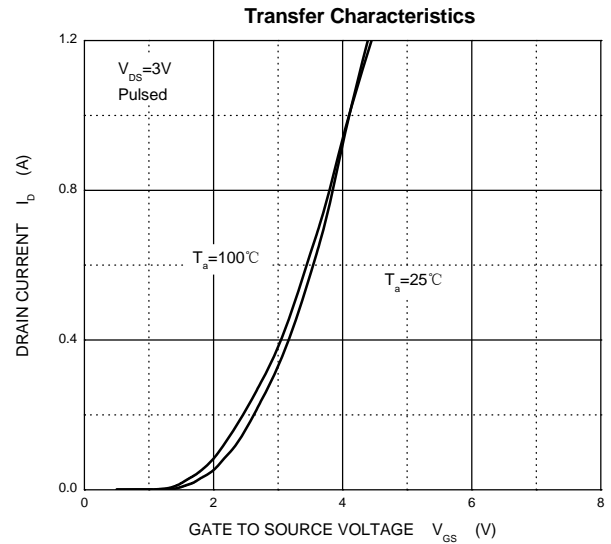
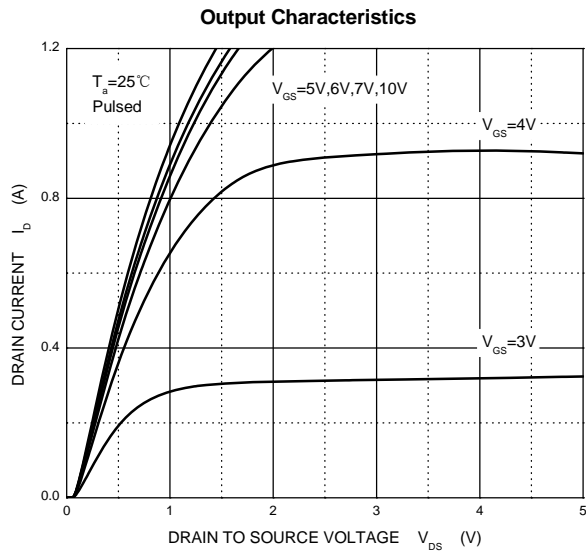
Parameter	Symbol	Test Condition	Min	Typ	Max	Units
Static Characteristics						
Drain-Source Breakdown Voltage	V _{DS}	V _{GS} = 0V, I _D = 250μA	60			V
Gate Threshold Voltage*	V _{GS(th)}	V _{DS} = V _{GS} , I _D = 1mA	1	1.3	2.5	V
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = 48V, V _{GS} = 0V			1	μA
Gate –Source leakage current	I _{GSS1}	V _{GS} = ±20V, V _{DS} = 0V			±10	μA
	I _{GSS2}	V _{GS} = ±10V, V _{DS} = 0V			±200	nA
	I _{GSS3}	V _{GS} = ±5V, V _{DS} = 0V			±100	nA
Drain-Source On-Resistance*	R _{DS(on)}	V _{GS} = 4.5V, I _D = 200mA		3	4	Ω
		V _{GS} = 10V, I _D = 500mA		2	3	Ω
Diode Forward Voltage	V _{SD}	V _{GS} = 0V, I _S = 100mA			1.2	V
Recovered charge	Q _r	V _{GS} = 0V, I _S = 300mA, V _R = 25V, dI _S /dt = -100A/μS		30		nC
Dynamic Characteristics**						
Input Capacitance	C _{iss}	V _{DS} = 10V, V _{GS} = 0V, f = 1MHz			40	pF
Output Capacitance	C _{oss}				30	pF
Reverse Transfer Capacitance	C _{rss}				10	pF
Switching Characteristics**						
Turn-On Delay Time	t _{d(on)}	V _{GS} = 10V, V _{DD} = 50V, R _G = 50Ω, R _{GS} = 50Ω, R _L = 250Ω			10	ns
Turn-Off Delay Time	t _{d(off)}				15	ns
Reverse recovery Time	t _{rr}	V _{GS} = 0V, I _S = 300mA, V _R = 25V, dI _S /dt = -100A/μS		30		ns
GATE-SOURCE ZENER DIODE						
Gate-Source Breakdown Voltage	BV _{GSO}	I _{GS} = ±1mA (Open Drain)	±21.5		±30	V

Notes :

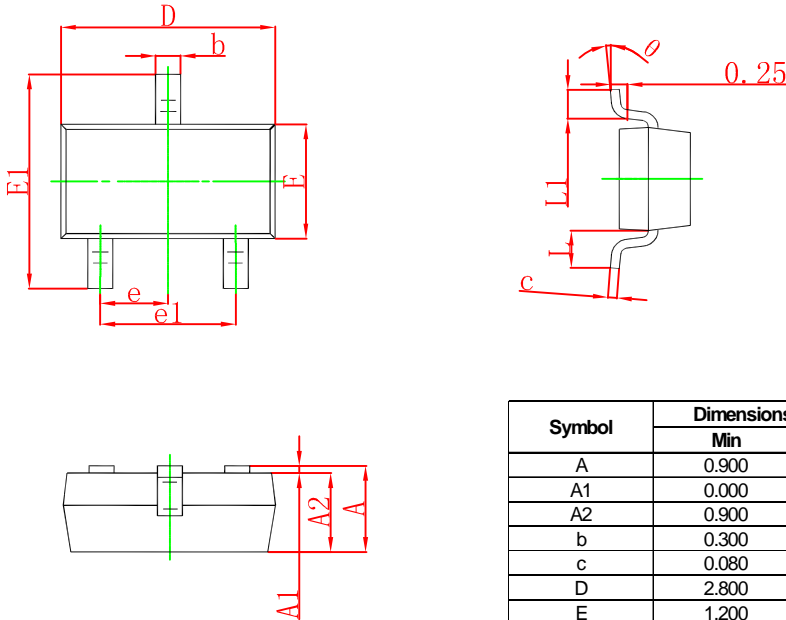
*Pulse Test : Pulse Width ≤ 300μs, Duty Cycle ≤ 2%.

**These parameters have no way to verify.

Typical Characteristics

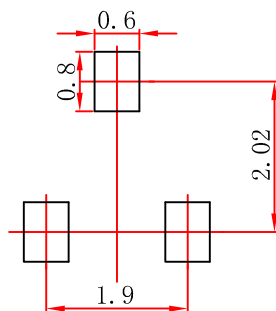


SOT-23 Package Outline Dimensions



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	0.900	1.150	0.035	0.045
A1	0.000	0.100	0.000	0.004
A2	0.900	1.050	0.035	0.041
b	0.300	0.500	0.012	0.020
c	0.080	0.150	0.003	0.006
D	2.800	3.000	0.110	0.118
E	1.200	1.400	0.047	0.055
E1	2.250	2.550	0.089	0.100
e	0.950 TYP		0.037 TYP	
e1	1.800	2.000	0.071	0.079
L	0.550 REF		0.022 REF	
L1	0.300	0.500	0.012	0.020
θ	0°	8°	0°	8°

SOT-23 Suggested Pad Layout



- Note:
1. Controlling dimension; in millimeters.
 2. General tolerance: $\pm 0.05\text{mm}$.
 3. The pad layout is for reference purposes only.